



*IFW*  
PATENT APPLICATION  
Docket No. 9903-067  
Client No. S02US034

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Hyun-Ho KIM, et al.

Serial No. 10/620,745 Examiner: Tran, Thien F

Filed: July 15, 2003 Group Art Unit: 2811

For: IN-LINE DIE ATTACHING AND CURING APPARATUS FOR A  
MULTI-CHIP PACKAGE

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE TO RESTRICTION REQUIREMENT**

Responsive to the Restriction Requirement, dated August 20, 2004, Applicant hereby  
elects Group II (claims 1-19), without traverse.

**Customer No. 20575**

Respectfully submitted,

MARGER JOHNSON & McCOLLOM, PC

Hosoon Lee  
Limited Recognition Under 37 CFR § 10.9(b)

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Li Mei Vermilya